Amendments to the Claims:

The listing of claims will replace all prior versions, and listings, of claims in the above-captioned application.

1. (Currently amended): A process ~~An epoxy resin composition~~ for producing a printed wiring board, which comprises using an epoxy resin composition in producing a printed wiring board; said epoxy resin composition comprising an epoxy resin, a phenol novolac resin, a curing accelerator and a silica filler; wherein said ~~, characterized in that, as the~~ silica filler ~~,~~ is ~~used~~ a silica filler which has a shape having at least two planes, and has an average particle diameter between 0.3 μm and 10 μm and a relative surface area between 8 m^2/g and 30 m^2/g.

2. (Currently amended): A process ~~An epoxy resin composition~~ for producing a printed wiring board as described in claim 1, wherein ~~characterized in that, as~~ said silica filler ~~defined in claim 1,~~ is ~~used~~ a silica filler having at least two planes in the shape, an average particle diameter between 0.3 μm and 10 μm and a relative surface area between 10 m^2/g and 20 m^2/g.

3. (Currently amended): A process ~~An epoxy resin composition~~ for producing a printed wiring board as described in claim 1 ~~or 2~~, wherein ~~characterized in that~~ said silica filler ~~defined in claim 1 or 2~~ is added in an amount of from 3% to 80% by weight per the solid content of the resin.

4. (Currently amended): A process ~~An epoxy resin composition~~ for producing a printed wiring board as described in ~~any one of claims~~ claim 1 ~~to 3~~, wherein ~~characterized in that, as~~ said silica filler ~~defined in claim 1,~~ is ~~used~~ a silica filler having an electric conductivity of 15 μs or less.

5. (Currently amended): A process ~~An epoxy resin composition~~ for producing a printed wiring board as described in ~~any one of claims~~ claim 1 ~~to 4~~, wherein ~~characterized in that, as~~ said silica

filler ~~defined in claim 1 or 2,~~ is ~~used~~ a silica filler which has been vitrified through melting at a temperature of 1800°C or higher.

6. (Currently amended): A process ~~An epoxy resin composition~~ for producing a printed wiring board as described in ~~any one of claims~~ claim 1 ~~to 5~~, wherein ~~characterized in that, as~~ said epoxy resin ~~,~~ is ~~used~~ an epoxy resin having a bromine content of between 5% and 20% by weight per the solid content of the resin without silica filler and containing an epoxy resin obtained by reacting a dihydric phenol with a bisphenol A type epoxy resin in an amount of between 40% and 100% by weight based on the whole amount of the epoxy resin solid content.

7. (Currently amended): A process ~~An epoxy resin composition~~ for producing a printed wiring board as described in ~~any one of claims~~ claim 1 ~~to 5~~, wherein ~~characterized in that, as~~ said epoxy resin ~~,~~ is ~~used~~ an epoxy resin having a bromine content of between 5% and 20% by weight per the solid content of the resin without silica filler and containing an epoxy resin possessing a dicyclopentadienyl structure in an amount of between 40% and 100% by weight based on the whole amount of the epoxy resin solid content.

8. (Currently amended): A process ~~An epoxy resin composition~~ for producing a printed wiring board as described in ~~any one of claims~~ claim 1 ~~to 5~~, wherein ~~characterized in that, as~~ said epoxy resin ~~,~~ is ~~used~~ an epoxy resin having a bromine content of between 5% and 20% by weight per the solid content of the resin without silica filler and containing of a novolac type epoxy resin in an amount of between 40% and 100% by weight based on the whole amount of the epoxy resin solid content.

9. (Currently amended): A process ~~An epoxy resin composition~~ for producing a printed wiring board as described in ~~any one of claims~~ claim 1 ~~to 5~~, wherein ~~characterized in that, as~~ said epoxy resin composition ~~,~~ is ~~used~~ a bromine-free epoxy resin composition.

10. (Currently amended): A process ~~prepreg~~ for producing a printed wiring board, which comprises using a prepreg in producing a printed wiring board; said ~~characterized in that the~~ prepreg is obtained by impregnating a reinforcing material with an epoxy resin composition for a printed wiring board ~~as described in any one of claims1 to 9~~ and drying said composition to B-stage; said epoxy resin composition comprising an epoxy resin, a phenol novolac resin, a curing accelerator, and a silica filler which has a shape having at least two planes and has an average particle diameter between 0.3 μm and 10 μm and a relative surface area between 8 m^2/g and 30 m^2/g.

11. (Currently amended): A process ~~laminated board~~ for producing a printed wiring board, which comprises using a laminate board in producing a printed wiring board; said laminate ~~characterized in that the~~ board is obtained by gluing a prepreg as described in claim 10 to a surface of a metal foil and hot pressing them.

12. (Currently amended): A printed wiring board, which ~~characterized in that the board~~ is obtained by using a laminated board for a printed wiring board ~~as described in claim 11~~; said laminate board is obtained by gluing a prepreg as described in claim 10 to a surface of a metal foil and hot pressing them.

13. (New): A process for producing a printed wiring board as described in claim 1, which comprises the following steps:

(1) preparing a prepreg for a printed wiring board, by preparing a varnish of said epoxy resin composition with an organic solvent, impregnating the varnish into a glass cloth, and drying it in an oven to make it into a semi-cured state (B-stage);

(2) manufacturing a laminated board for a printed wiring board by stacking a prescribed number of sheets of said prepreg and hot-pressing them through laminate molding, and placing a metal foil on one or both sides of the prescribed number of the prepreg sheets stacked for printed wiring board and laminate-molded to yield a metal foil-clad laminated board; and

(3) forming a circuit on an outer layer of the laminated board for printed wiring board to yield a printed wiring board.

14. (New): A process for producing a printed wiring board, which comprises the following steps:

(1) preparing a prepreg for a printed wiring board, by preparing a varnish of said epoxy resin composition with an organic solvent, impregnating the varnish into a glass cloth, and drying it in an oven to make it into a semi-cured state (B-stage); wherein said epoxy resin composition comprises an epoxy resin, a phenol novolac resin, a curing accelerator, and a silica filler having a shape having at least two planes and having an average particle diameter between 0.3 □and 10□ and a relative surface area between 8 m^2/g and 30 m^2/g;

(2) manufacturing a laminated board for a printed wiring board, by stacking a prescribed number of sheets of said prepreg and hot-pressing them through laminate molding, and placing a metal foil on one or both sides of the prescribed number of the prepreg sheets stacked for printed wiring board and laminate-molded to yield a metal foil-clad laminated board; and

(3) forming a circuit on an outer layer of the laminated board for printed wiring board to yield a printed wiring board.

15. (New): A printed wiring board, which is obtained by the process as described in claim 13.

16. (New): A printed wiring board, which is obtained by the process as described in claim 14.

It is believed that no fees are due in connection with the filing of this Preliminary Amendment. However, if any fees are due, the Commissioner is hereby authorized to deduct said fees from Meyertons, Hood, Kivlin, Kowert & Goetzel Deposit Account No. 50-1505/5682-00900/EBM.

Respectfully submitted,

Eric B. Meyertons
Reg. No. 34,876

Attorney for Applicant

MEYERTONS, HOOD, KIVLIN, KOWERT & GOETZEL, P.C.
P.O. BOX 398
AUSTIN, TX 78767-0398
(512) 853-8800 (voice)
(512) 853-8801 (facsimile)

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